

This article was downloaded by:

On: 22 January 2011

Access details: *Access Details: Free Access*

Publisher *Taylor & Francis*

Informa Ltd Registered in England and Wales Registered Number: 1072954 Registered office: Mortimer House, 37-41 Mortimer Street, London W1T 3JH, UK



The Journal of Adhesion

Publication details, including instructions for authors and subscription information:

<http://www.informaworld.com/smpp/title~content=t713453635>

Organically Modified Silicates (Ormosils) as Adhesives for Siliceous Surfaces

H. Schmidt^a

^a Fraunhofer-Institut für Silicatforschung, Würzburg, WEST GERMANY

To cite this Article Schmidt, H.(1987) 'Organically Modified Silicates (Ormosils) as Adhesives for Siliceous Surfaces', The Journal of Adhesion, 22: 2, 77 – 80

To link to this Article: DOI: 10.1080/00218468708074992

URL: <http://dx.doi.org/10.1080/00218468708074992>

PLEASE SCROLL DOWN FOR ARTICLE

Full terms and conditions of use: <http://www.informaworld.com/terms-and-conditions-of-access.pdf>

This article may be used for research, teaching and private study purposes. Any substantial or systematic reproduction, re-distribution, re-selling, loan or sub-licensing, systematic supply or distribution in any form to anyone is expressly forbidden.

The publisher does not give any warranty express or implied or make any representation that the contents will be complete or accurate or up to date. The accuracy of any instructions, formulae and drug doses should be independently verified with primary sources. The publisher shall not be liable for any loss, actions, claims, proceedings, demand or costs or damages whatsoever or howsoever caused arising directly or indirectly in connection with or arising out of the use of this material.

Long Abstract

Organically Modified Silicates (Ormosils) as Adhesives for Siliceous Surfaces†

H. SCHMIDT

Fraunhofer-Institut für Silicatforschung, Würzburg, WEST GERMANY

(Received November 12, 1986)

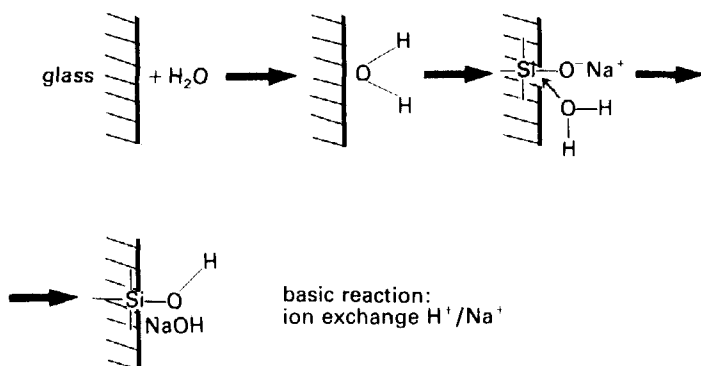
KEY WORDS Adhesion promoters; adhesion to glass; organically modified silicates; coupling agents; durability; silanes.

1 INTRODUCTION

Adhesion to glass surfaces still may be a problem under "heavy duty" conditions such as temperature and moisture or both. In many cases the problem may be overcome by use of adhesion promoters such as reactive silanes. These silanes remove water films from the glass surface by chemical reaction, are able to form chemical bonds to the glass surface and, in addition to this, can have an affinity to the sealing material to be used. A decay of adhesion strength between glass and a seal under wet conditions is

† This is the long abstract of a paper presented orally at the Tenth Annual Meeting of The Adhesion Society, Inc., Williamsburg, Virginia, U.S.A., February 22-27, 1986.

caused by the following effect:



The formation of NaOH leads to an alkaline media interface between seal and glass surface which causes a network degradation of the glass and a subsequent loss of adhesion. The magnitude of the effect depends strongly on the chemical durability of the glass substrate used. Especially, if hot sealing procedures have to be used, serious difficulties due to wetting problems during the sealing procedure and due to a water film remaining on the glass surface can appear.

A special hot sealing material was developed which was proved to be able to overcome most of the described problems:

- a) The material should be "glass-like". Therefore, a silica based polymer with a $\equiv\text{Si}-\text{O}-\text{Si}\equiv$ backbone was chosen.
- b) The material should be thermoplastic. That means the network connectivity of a pure inorganic (non-thermoplastic) polymer had to be reduced. Therefore, $\text{C}_6\text{H}_5-\text{Si}-\text{C}_6\text{H}_5$ groups were introduced. It was well known that these groups can cause thermoplasticity.
- c) Residual groups like $\equiv\text{Si}-\text{OR}$ or $\equiv\text{Si}-\text{OH}$ should remain in the polymer in order to form reactive bonds to the glass surface.
- d) Flexibility and photocurability should be obtained for reasons of application improvement. Therefore, a second type of

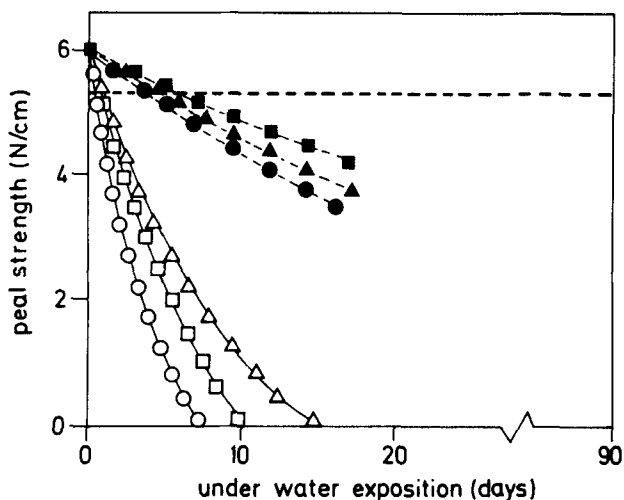


FIGURE 1 Peel strength decay curves of 1 cm Al-strips sealed on glass polyamide: untreated: $\triangle\triangle\triangle$

treated: $\blacktriangle\blacktriangle\blacktriangle$

vinylacetate/vinylchloride copolymer:

untreated: $\circ\circ\circ$

treated: $\bullet\bullet\bullet$

Surlyn: untreated: $\square\square\square$

treated: $\blacksquare\blacksquare\blacksquare$

$(C_6H_5)_2SiO/TiO_2/CH_2=CH(CH_3)SiO$ based copolymer:---

Treatment: Glass surfaces treated with an epoxy silane as adhesion promoter.

network by vinyl polymerization was introduced into the polymer by use of $CH_3-Si-CH=CH_2$ groupings.

As a result, a three-component system using sol-gel techniques was synthesized from $Si(OC_2H_5)_4$, $(C_2H_5O)_2Si(CH_3)CH=CH_2$ and $(C_6H_5)_2Si(OH)_2$ or $Ti(OC_2H_5)_4$ as starting compounds.^{1,2,3} By proper choice of composition, hydrolysis and condensation and thermal or photocuring, hot melts can be obtained with sealing temperatures between 80 and 160°C as desired. Figure 1 shows the sealing strength (peel strength) of aluminum strips sealed to a glass surface in comparison to other polymers with and without using an adhesion promoter. Figure 2 shows the IR-controlled thermal curing. The OH-group content has to be adjusted for an optimal sealing strength.

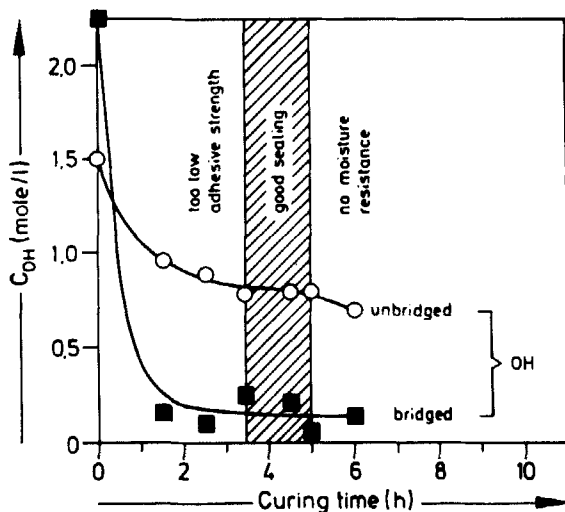


FIGURE 2 SiOH group concentrations for the system based on $(C_6H_5)_2SiO/SiO_2/CH_2=CH(CH_3)SiO$ as received from IR measure units; the hatched area represents the range of high peel strength and high moisture resistance according to Figure 1.

References

1. H. Schmidt, G. Tünker and H. Scholze, DP 30 11 761, 26.03.80 (EP 36 648, 20.03.81, US-Patent 4,374,696, 20.03.81).
2. H. Schmidt, H. Scholze and G. Tünker, *J. Non-Cryst. Solids* **80**, 557–563 (1986).
3. H. Schmidt, G. Philipp, H. Patzelt and H. Scholze, "Glass sealings by sol-gel derived organically modified silicates." Collected papers, XIV Intl. Congr. on Glass, New Delhi (1986), pp. 429–436.